

### Features

- Very low FOM  $R_{DS(on)} \times Q_G$
- 100% avalanche tested

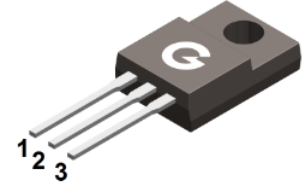
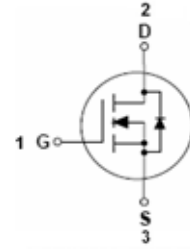
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### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)

### Mechanical Data

- Case: ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



ITO-220AB

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
SJM60R099F	ITO-220AB	50 pcs / Tube	SJM60R099F

## Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	600	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current ( $T_C = 25^\circ\text{C}$ )	$I_D$	13	A
Continuous Drain Current ( $T_C = 100^\circ\text{C}$ )		8	A
Pulsed Drain Current	$I_{DM}$	91	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	300	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	43	W
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	2.9	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	-	-	62	$^\circ\text{C}/\text{W}$

### Electrical Characteristics (@ $T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	600	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Drain-Source On-resistance *1	$V_{GS} = 10V, I_D = 19A$	-	-	99	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	3.5	4.5	V
<b>Dynamic Characteristics</b>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0V$	-	2270	-	pF
$C_{OSS}$	Output Capacitance	$V_{DS} = 400V$	-	58	-	
$C_{RSS}$	Reverse Transfer Capacitance	$f = 1.0MHz$	-	3	-	
<b>Switching Characteristics</b>						
$t_{d(ON)}$	Turn-on Delay Time *3	$V_{DD} = 400V$	-	17	-	ns
$t_r$	Turn-on Rise Time *3	$V_{GS} = 10V$	-	10	-	
$t_{d(OFF)}$	Turn-Off Delay Time *3	$R_G = 10\Omega$	-	86	-	
$t_f$	Turn-Off Fall Time *3	$I_D = 19A$	-	11	-	
$Q_G$	Total Gate-Charge	$V_{DD} = 400V$	-	58	-	nC
$Q_{GS}$	Gate to Source Charge	$V_{GS} = 10V$	-	13.5	-	
$Q_{GD}$	Gate to Drain (Miller) Charge	$I_D = 10A$	-	23	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage *1	$I_{SD} = 19A, V_{GS} = 0V$	-	0.9	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F = 19A, V_{GS} = 0V$	-	440	-	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt = 100 A/\mu s$	-	7.2	-	$\mu C$

Notes:

1. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
2. The  $E_{AS}$  data shows Max. rating. The test condition is  $V_{DD} = 50V, V_{GS} = 15V, L = 10mH$
3. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@  $T_J = 25^\circ\text{C}$  unless otherwise specified)

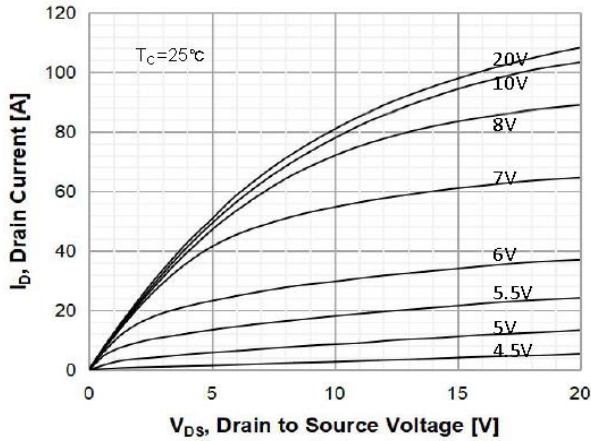


Fig 1 Typical Output Characteristics

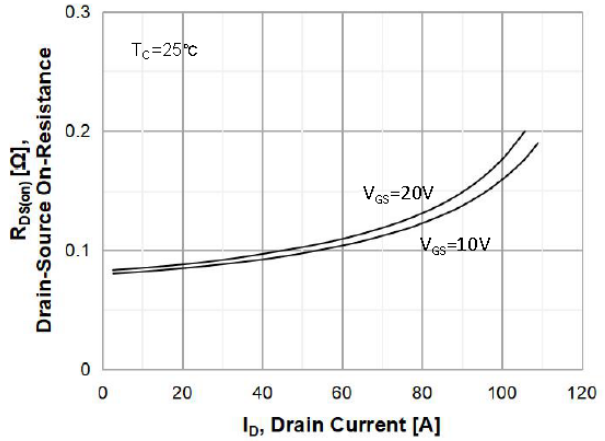


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

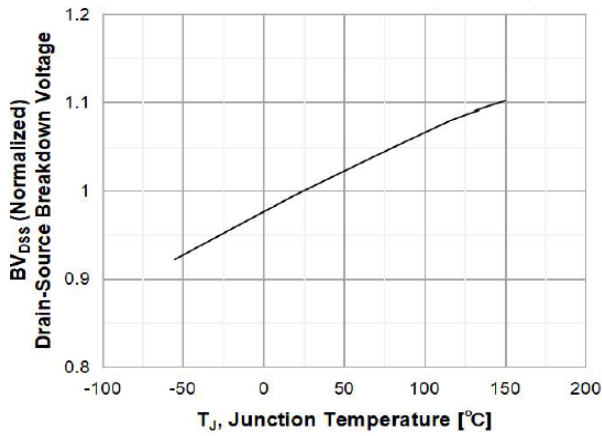


Fig 3 Normalized Breakdown Voltage vs. Junction Temperature

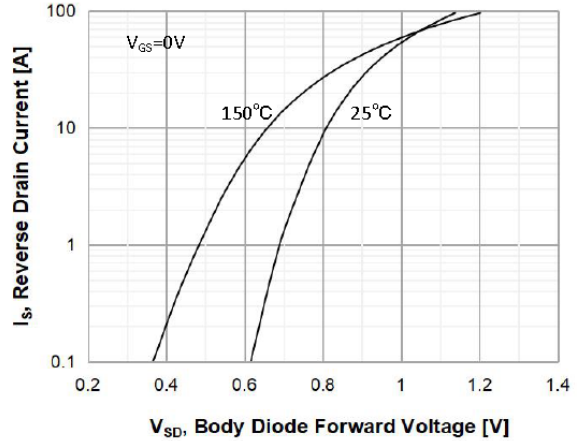


Fig 4 Body-Diode Characteristics

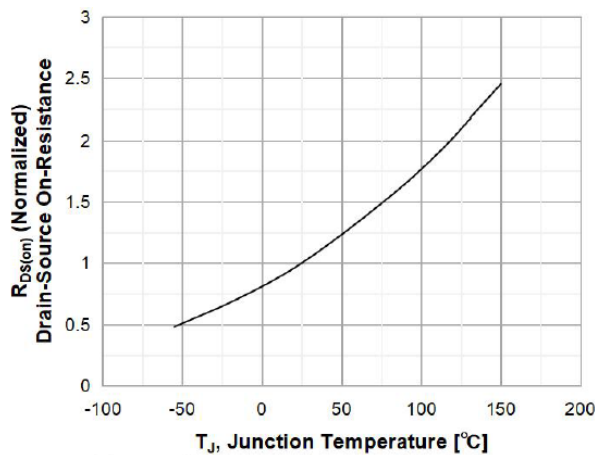


Fig 5 Normalized On-Resistance vs. Junction Temperature

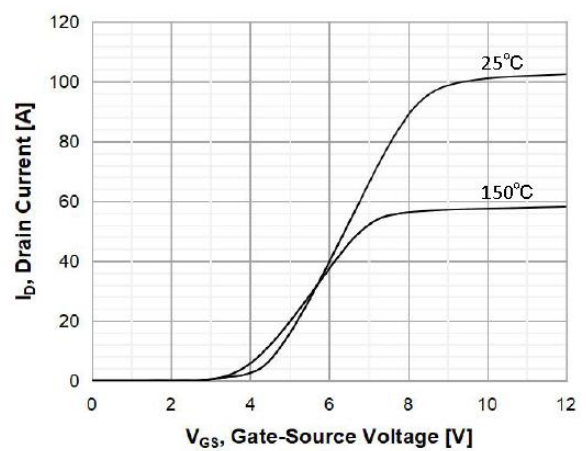


Fig 6 Transfer Characteristics

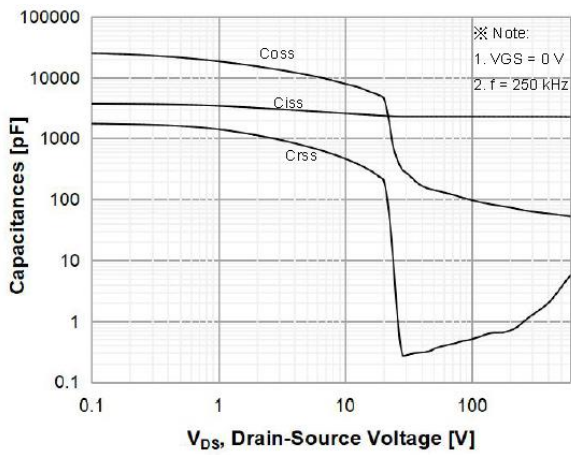


Fig 7 Capacitance Characteristics

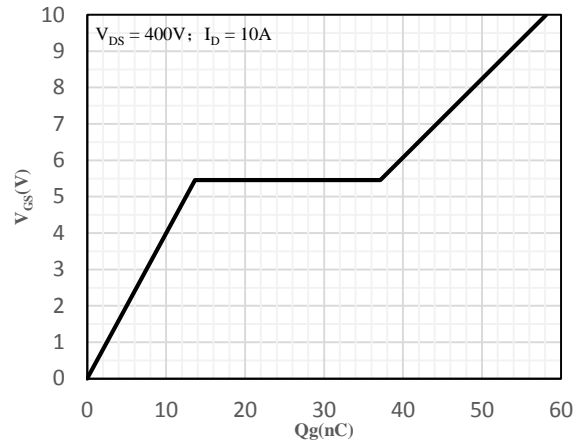


Fig 8 Gate-Charge Characteristics

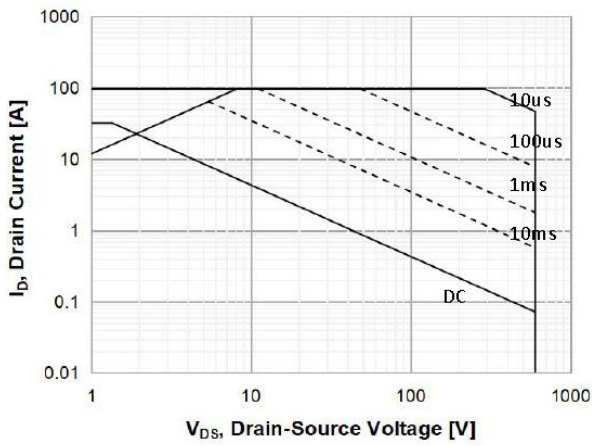


Fig 9 Safe Operation Area

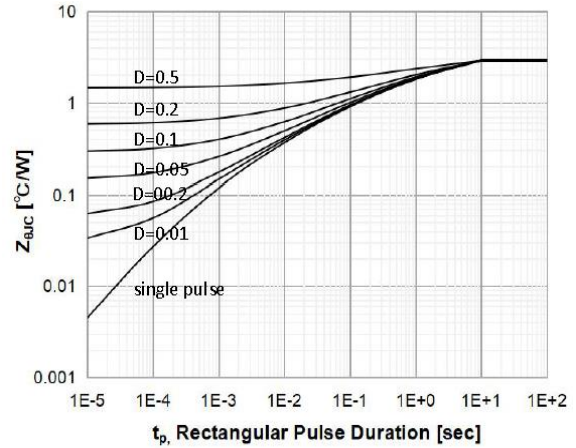
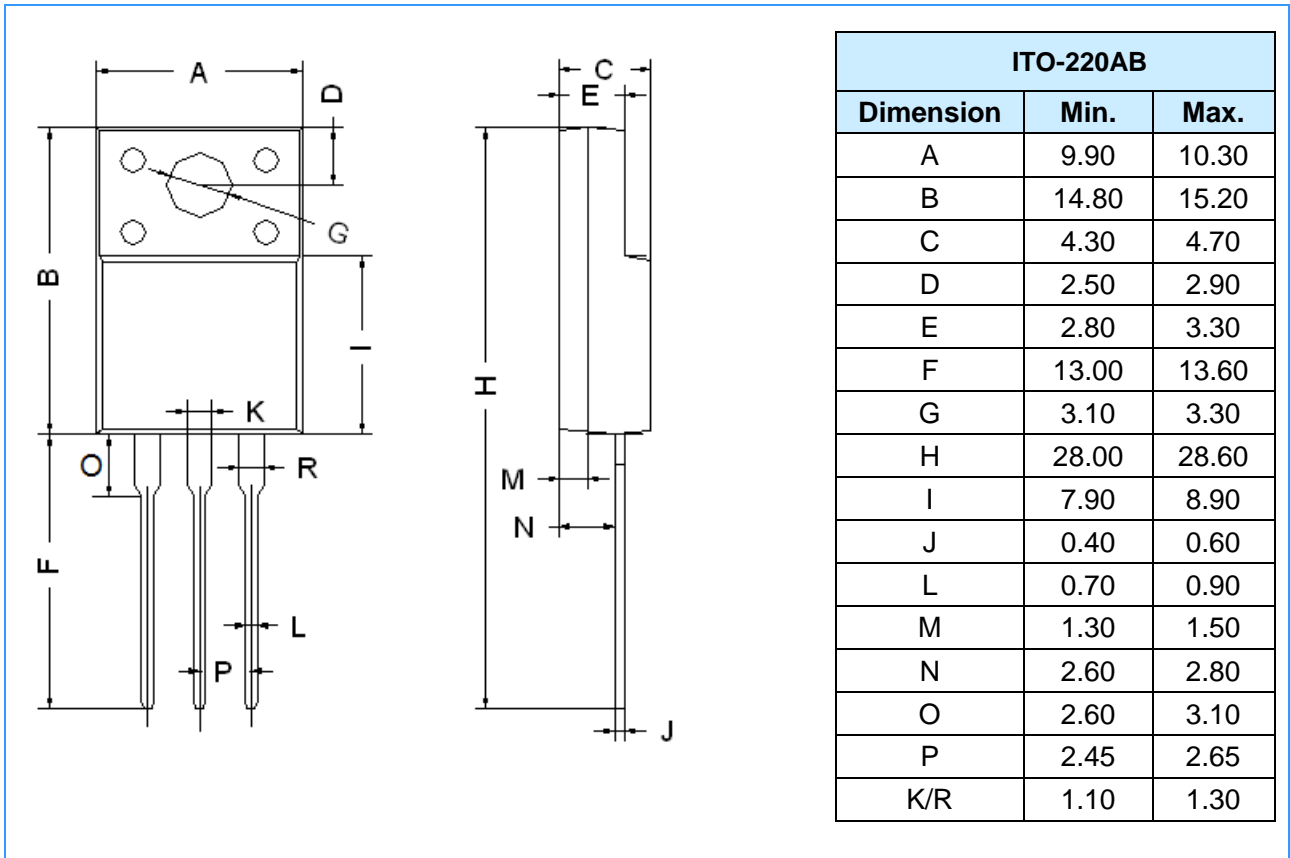


Fig 10 Maximum transient thermal impedance

**Package Outline Dimensions** (Unit: mm)



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